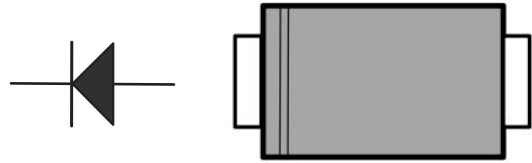


Surface Mount Ultrafast Recovery Rectifier

Parameter	Value	Unit
V_{RRM}	50~1000	V
$I_{F(AV)}$	2.0	A



SMAF

Features

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Easy to pick and place
- High efficiency

Applications

- For use in high-frequency rectification and free-wheeling applications in switching-mode converters and inverters for consumer electronics, computer systems, and telecommunications.

Absolute Maximum Ratings and Characteristics (at $T_J = 25^\circ\text{C}$ unless otherwise specified)

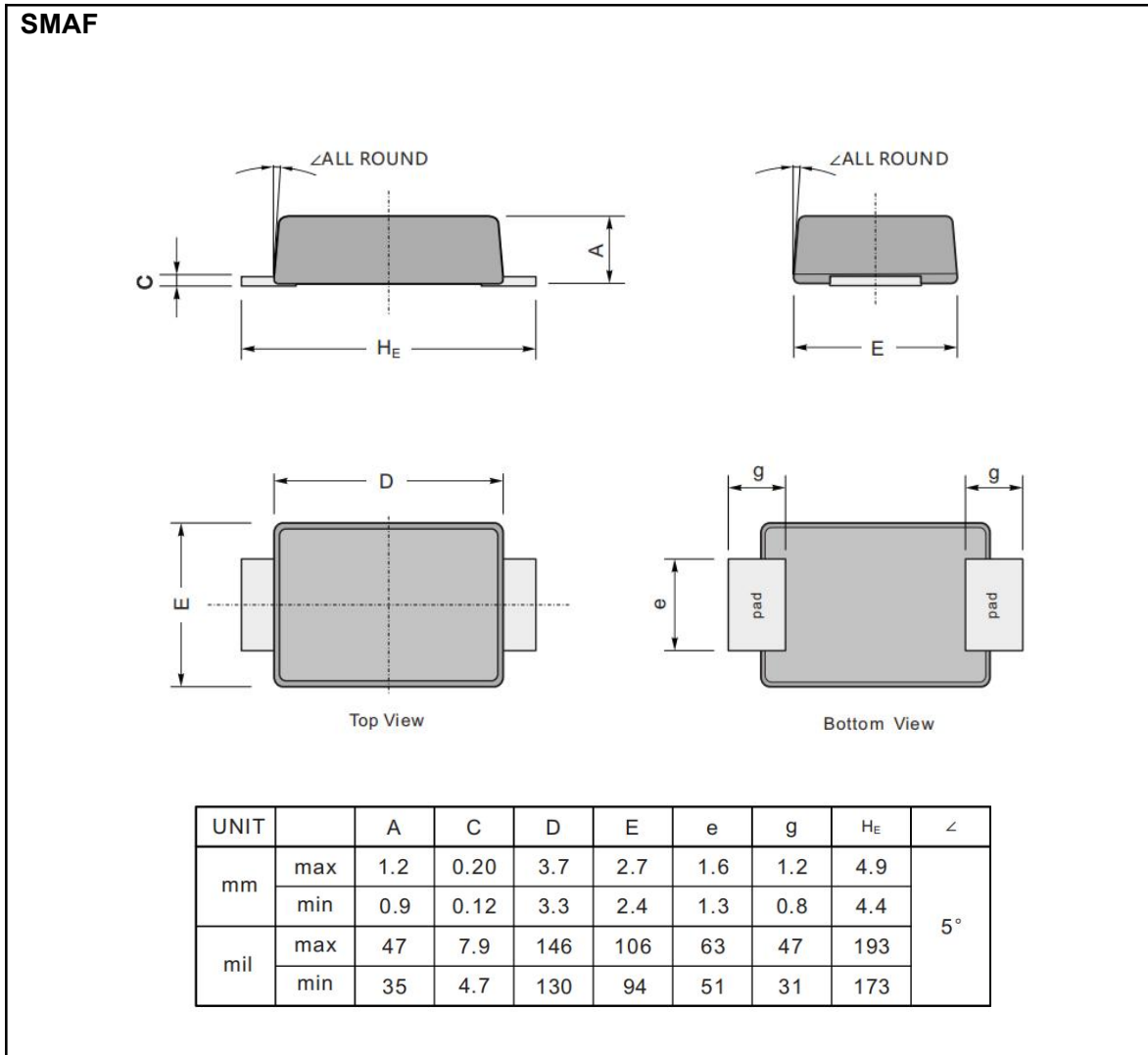
Parameter	Symbol	US2AF	US2BF	US2DF	US2GF	US2JF	US2KF	US2MF	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at $T_C=125^\circ\text{C}$	$I_{F(AV)}$	2.0							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	50							A
Maximum Instantaneous Forward Voltage at 2A	V_F	1.0		1.3		1.65			V
Maximum DC Reverse Current at Rated DC Blocking Voltage $T_a=25^\circ\text{C}$ $T_a=125^\circ\text{C}$	I_R	5 100							μA
Maximum Reverse Recovery Time ⁽¹⁾	t_{rr}	50				75			ns
Typical Thermal Resistance ⁽²⁾	$R_{\theta JA}$ $R_{\theta JC}$	65 20							$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150							$^\circ\text{C}$

Notes:

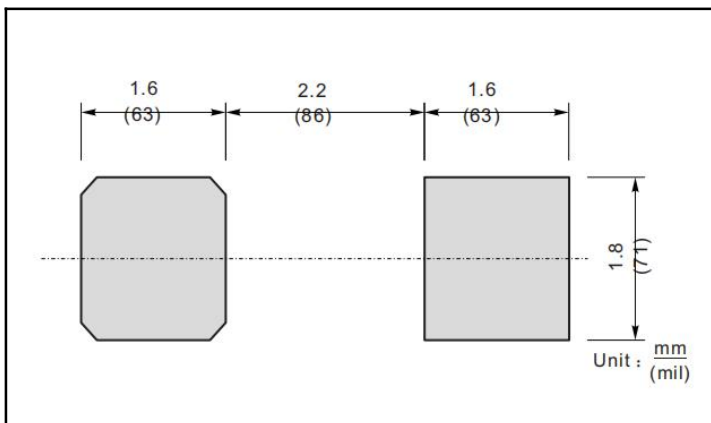
- (1) Measured with $I_F = 0.5\text{A}$, $I_R = 1\text{A}$, $I_{rr} = 0.25\text{A}$.
 (2) P.C.B. mounted with 2.0" X 2.0" (5 X 5cm) copper pad areas.

Package outlines

Plastic surface mounted package; 2 leads



The recommended mounting pad size



Marking

Type number	Marking code
US2AF	US2AF
US2BF	US2BF
US2DF	US2DF
US2GF	US2GF
US2JF	US2JF
US2KF	US2KF
US2MF	US2MF

***Important Usage Information and Disclaimer**

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